

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Canceled)
2. (Previously Presented) A film-like article comprising:
a thin film integrated circuit capable of storing information described on the film-like article; and
an antenna connected to the thin film integrated circuit,
wherein the thin film integrated circuit is mounted inside the film-like article, and the antenna is mounted on a surface of the film-like article.
3. (Canceled)
4. (Previously Presented) A film-like article according to Claim 2,
wherein when the thickness of the film-like article is D , a position to dispose the thin film integrated circuit X may be set so as to satisfy $(1/2) \cdot D - 30 \mu\text{m} < X < (1/2) \cdot D + 30 \mu\text{m}$.
5. (Previously Presented) A film-like article comprising:
a thin film integrated circuit capable of storing information described on the film-like article; and
an antenna connected to the thin film integrated circuit,
wherein the thin film integrated circuit and the antenna are mounted on a surface of the film-like article.

6. (Previously Presented) A film-like article comprising:
a thin film integrated circuit capable of storing information described on the film-like article; and
an antenna connected to the thin film integrated circuit,
wherein the thin film integrated circuit is mounted on a surface of the film-like article, and
the antenna is mounted inside the film-like article.

7.-8. (Canceled)

9. (Previously Presented) A film-like article according to Claim 2, further comprising
a substrate,
wherein an opening with slits is provided in the substrate,
wherein the thin film integrated circuit is electrically connected to the antenna through the opening in the substrate.

10. (Previously Presented) A film-like article according to Claim 5, further comprising:
a substrate,
wherein an opening with slits is provided in the substrate,
wherein the thin film integrated circuit is electrically connected to the antenna through the opening in the substrate.

11. (Previously Presented) A film-like article according to Claim 6, further comprising:
a substrate,
wherein an opening with slits is provided in the substrate,

wherein the thin film integrated circuit is electrically connected to the antenna through the opening in the substrate.

12.-13. (Canceled)

14. (Original) A film-like article according Claim 2,
wherein the thin film integrated circuit has light-transmitting characteristic.

15. (Original) A film-like article according Claim 5,
wherein the thin film integrated circuit has light-transmitting characteristic.

16. (Original) A film-like article according Claim 6,
wherein the thin film integrated circuit has light-transmitting characteristic.

17.-18. (Canceled)

19. (Original) A film-like article according to Claim 2,
wherein the thin film integrated circuit has an insulating film containing nitrogen.

20. (Original) A film-like article according to Claim 5,
wherein the thin film integrated circuit has an insulating film containing nitrogen.

21. (Original) A film-like article according to Claim 6,
wherein the thin film integrated circuit has an insulating film containing nitrogen.

22.-23. (Canceled)

24. (Original) A film-like article according to Claim 2,

wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm .

25. (Original) A film-like article according to Claim 5,
wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm .

26. (Original) A film-like article according to Claim 6,
wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm .

27.-28. (Canceled)

29. (Original) A film-like article according to Claim 2,
wherein the thin film integrated circuit has a semiconductor film containing
hydrogen of 1×10^{19} atoms/cm³ to 5×10^{20} atoms/cm³.

30. (Original) A film-like article according to Claim 5,
wherein the thin film integrated circuit has a semiconductor film containing
hydrogen of 1×10^{19} atoms/cm³ to 5×10^{20} atoms/cm³.

31. (Original) A film-like article according to Claim 6,
wherein the thin film integrated circuit has a semiconductor film containing
hydrogen of 1×10^{19} atoms/cm³ to 5×10^{20} atoms/cm³.

32. (Canceled)

33. (Currently Amended) A film-like article according to any one of Claims ~~28 to 32~~, 29 to 31,

wherein the semiconductor film includes a source, a drain, and a channel region,
and

the source, the drain, and the channel region are provided perpendicular to
direction of bending the film-like article.

34. (Canceled)

35. (Original) A film-like article according to Claim 2,
wherein the film-like article comprises a plurality of thin film integrated circuits,
and

the plurality of thin film integrated circuits are integrated with antennas.

36. (Original) A film-like article according to Claim 5,
wherein the film-like article comprises a plurality of thin film integrated circuits,
and

the plurality of thin film integrated circuits are integrated with antennas.

37. (Original) A film-like article according to Claim 6,
wherein the film-like article comprises a plurality of thin film integrated circuits,
and

the plurality of thin film integrated circuits are integrated with antennas.

38.-39. (Canceled)

40. (Original) A film-like article according to Claim 2,
wherein the film-like article is a business card.

41. (Original) A film-like article according to Claim 5,
wherein the film-like article is a business card.

42. (Original) A film-like article according to Claim 6,
wherein the film-like article is a business card.

43.-44. (Canceled)

45. (Previously Presented) A method for manufacturing a film-like article,
comprising the steps of:

forming a plurality of thin film integrated circuits over a first substrate;

transferring the plurality of thin film integrated circuits to a second substrate;

cutting the second substrate to cut out each of the plurality of thin film integrated
circuits;

connecting an antenna to a connection terminal of the thin film integrated circuit;

and

mounting the thin film integrated circuits and the antenna on a surface of a base
member of the film-like article.

46. (Canceled)

47. (Previously Presented) A method for manufacturing a film-like article,
comprising the steps of:

forming a plurality of thin film integrated circuits over a first substrate;

transferring the plurality of thin film integrated circuits to a second substrate;

cutting the second substrate to cut out each of the plurality of thin film integrated
circuits; and

enfolding each of the plurality of thin film integrated circuits in a base member of the film-like article,

forming an antenna on a surface of the base member of the film-like article so that the thin film integrated circuit and the antenna are connected through an opening formed on the base member of the film-like article.

48. (Canceled)